

## PART ONE: General description

needles

*Process name*

*Process Code*

07/19/00

*Last Update*

Udo Lang

*Author*

*Contact Information (Email)*

Silicon etching.

*General description of process*

## PART TWO: Details

*RIE Etching*

*Pressure Set*

185

*Oxygen Set*

0

*RF Power Set*

105

*CHF3 Set*

0

*End Point Set*

900

*SF6 Set*

55

*Process Time*

47

*min*

*Base Pressure Set*

150

## PART THREE: General Comments